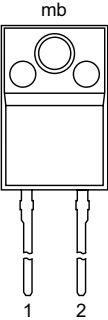
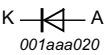


5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYC15X-600P	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 "full pack"	SOD113A

7. Marking

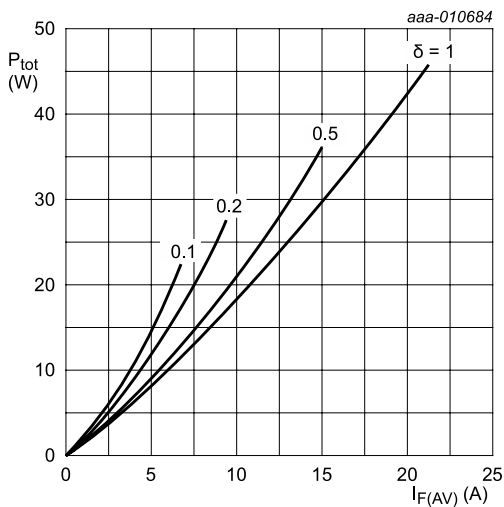
Table 4. Marking codes

Type number	Marking codes
BYC15X-600P	BYC15X-600P

8. Limiting values

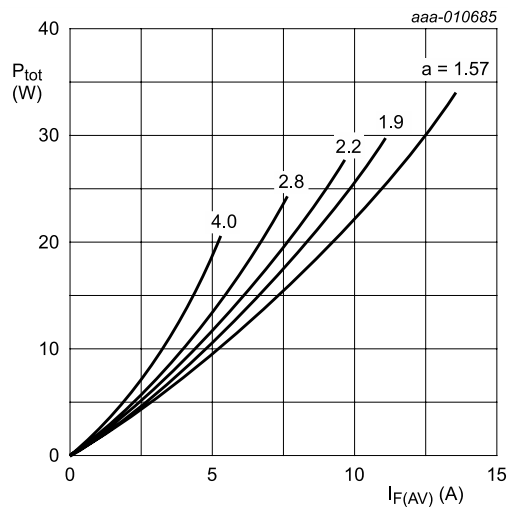
Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; Fig. 1; Fig. 2	15	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25 \mu s$; $T_h \leq 25 \text{ }^\circ C$; square-wave pulse	30	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10 \text{ ms}$; $T_{j(init)} = 25 \text{ }^\circ C$; sine-wave pulse; Fig. 3	180	A
		$t_p = 8.3 \text{ ms}$; $T_{j(init)} = 25 \text{ }^\circ C$; sine-wave pulse	200	A
T_{stg}	storage temperature		-65 to 175	$^\circ C$
T_j	junction temperature		175	$^\circ C$



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
 $V_o = 1.578$; $R_s = 0.027 \text{ } \Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$
 $V_o = 1.578$; $R_s = 0.027 \text{ } \Omega$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

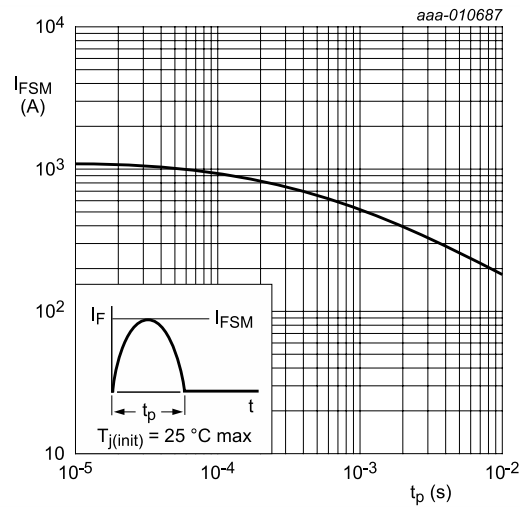


Fig. 3. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; Fig 4	-	-	4.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W

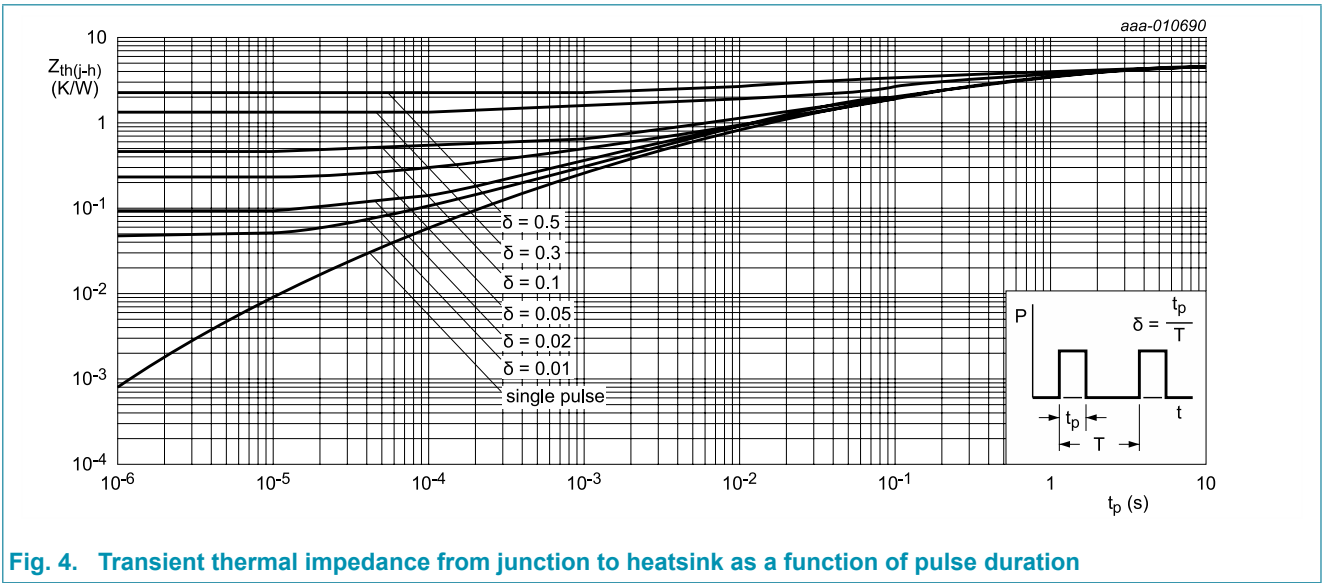


Fig. 4. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Isolation characteristics

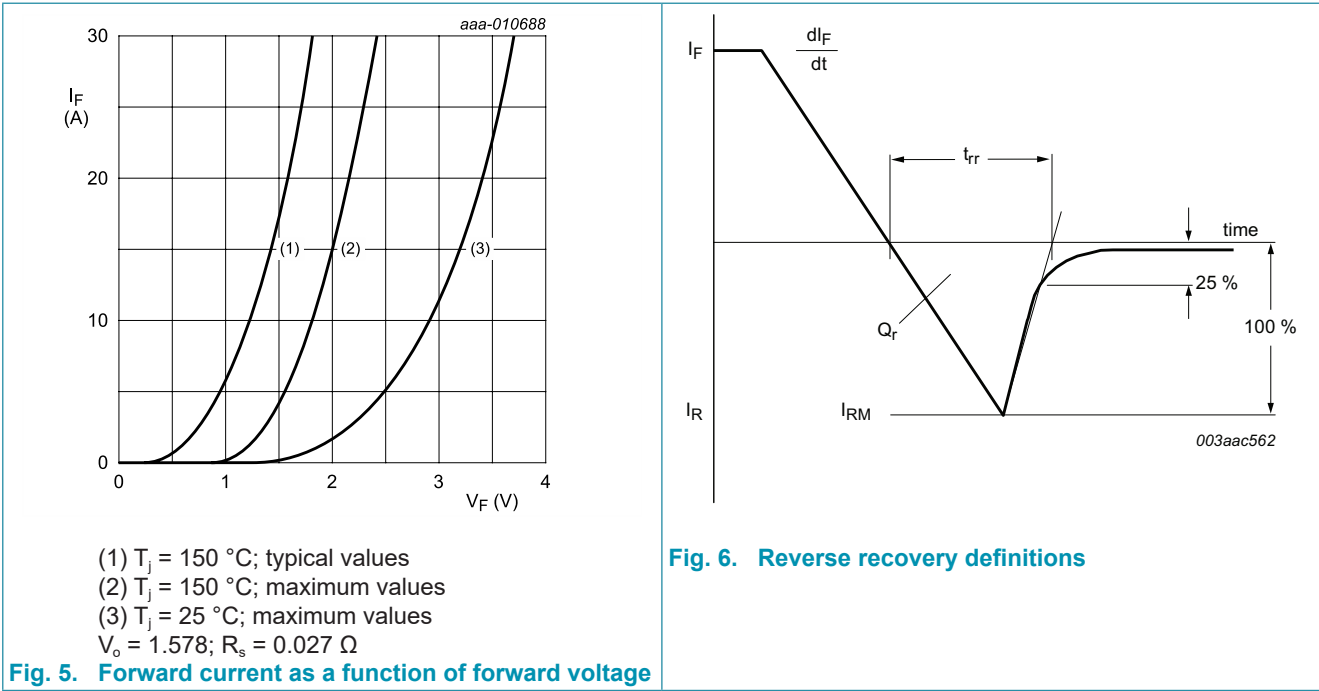
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C_{isol}	isolation capacitance	from cathode to external heatsink; f = 1 MHz	-	10	-	pF

11. Characteristics

Table 8. Characteristics

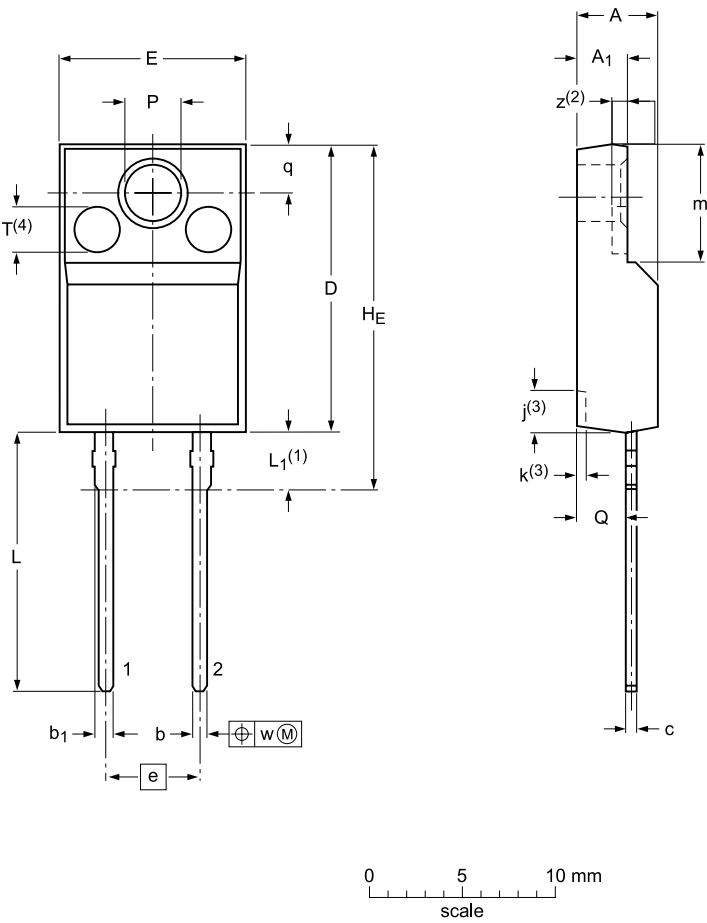
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _j = 25 °C; Fig. 5		-	2.7	3.2	V
		I _F = 15 A; T _j = 150 °C; Fig. 5		-	1.4	2	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	10	μA
		V _R = 500 V; T _j = 150 °C		-	-	1	mA
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 6		-	13	18	ns
		I _F = 15 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _j = 25 °C; Fig. 6		-	22	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 6		-	28	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 6		-	39	-	ns
I _{RM}	peak reverse recovery current	I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 6		-	2.1	-	A
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 6		-	5.8	-	A
Q _r	recovered charge	I _F = 15 A; dI _F /dt = 200 A/μs; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 6		-	30	-	V
		I _F = 15 A; dI _F /dt = 100 A/μs; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 6		-	115	-	V



12. Package outline

Plastic single-ended package; isolated heasink mounted;
1 mounting hole; 2-lead TO-220F 'full pack'

SOD113A



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₁	c	D	E	e	H _E max	j ⁽³⁾	k ⁽³⁾	L	L ₁ ⁽¹⁾	m	P	Q	q	T ⁽⁴⁾	W	z ⁽²⁾
max	4.6	3.1	0.9	1.1	0.7	15.8	10.3			2.7	0.8	14.4	3.3	6.5	3.2	2.8				
nom								5.08	19.0								2.6	2.55	0.4	0.8
min	4.0	2.5	0.7	0.9	0.4	15.2	9.7			1.7	0.4	13.5	2.8	6.3	3.0	2.3				

- Note
- 1. Terminals are uncontrolled within zone L1.
 - 2. z is depth of T.
 - 3. Dot lines area designs may vary.
 - 4. Eject pin mark is for reference only.

sod113a_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOD113A	2 LEADS TO220F					14-01-14 14-04-10

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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